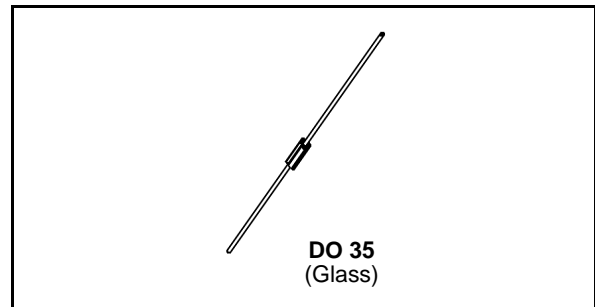


**1N 5711****SMALL SIGNAL SCHOTTKY DIODE****DESCRIPTION**

Metal to silicon junction diode featuring high break-down, low turn-on voltage and ultrafast switching. Primarily intended for high level UHF/VHF detection and pulse application with broad dynamic range. Matched batches are available on request.

**ABSOLUTE RATINGS** (limiting values)

Symbol	Parameter		Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage		70	V
I_F	Forward Continuous Current*	$T_a = 25^\circ\text{C}$	15	mA
P_{tot}	Power Dissipation*	$T_a = 25^\circ\text{C}$	430	mW
T_{stg} T_j	Storage and Junction Temperature Range		- 65 to 200 - 65 to 200	$^\circ\text{C}$
T_L	Maximum Lead Temperature for Soldering during 10s at 4mm from Case		230	$^\circ\text{C}$

THERMAL RESISTANCE

Symbol	Test Conditions	Value	Unit
$R_{th(j-a)}$	Junction-ambient*	400	$^\circ\text{C/W}$

ELECTRICAL CHARACTERISTICS**STATIC CHARACTERISTICS**

Symbol	Test Conditions		Min.	Typ.	Max.	Unit
V_{BR}	$T_{amb} = 25^\circ\text{C}$	$I_R = 10\mu\text{A}$	70			V
V_F^{**}	$T_{amb} = 25^\circ\text{C}$	$I_F = 1\text{mA}$			0.41	V
	$T_{amb} = 25^\circ\text{C}$	$I_F = 15\text{mA}$			1	
I_R^{**}	$T_{amb} = 25^\circ\text{C}$	$V_R = 50\text{V}$			0.2	μA

DYNAMIC CHARACTERISTICS

Symbol	Test Conditions			Min.	Typ.	Max.	Unit
C	$T_{amb} = 25^\circ\text{C}$	$V_R = 0\text{V}$	$f = 1\text{MHz}$			2	pF
τ	$T_{amb} = 25^\circ\text{C}$	$I_F = 5\text{mA}$	Krakauer Method			100	ps

* On infinite heatsink with 4mm lead length

** Pulse test: $t_p \leq 300\mu\text{s}$ $\delta < 2\%$.

Matched batches available on request. Test conditions (forward voltage and/or capacitance) according to customer specification.

Figure 1. Forward current versus forward voltage at low level (typical values).

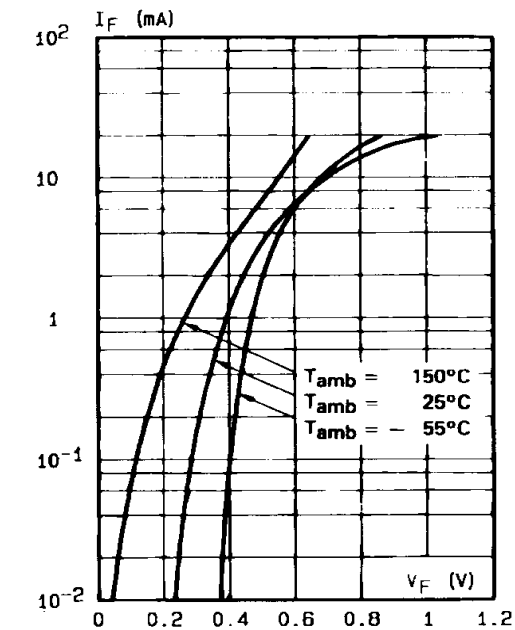


Figure 2. Capacitance C versus reverse applied voltage V_R (typical values).

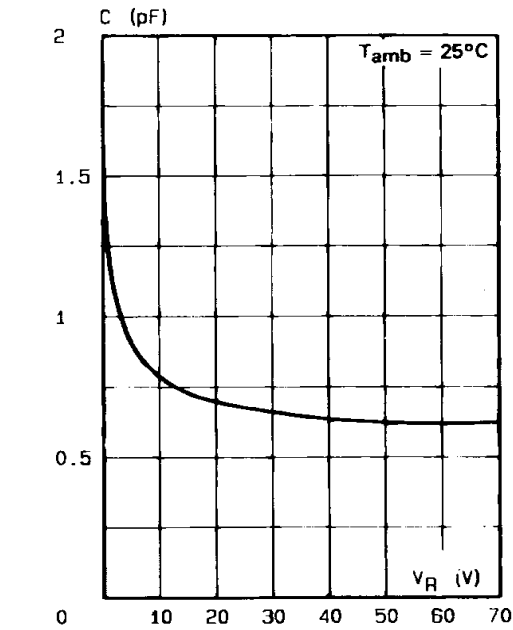


Figure 3. Reverse current versus ambient temperature.

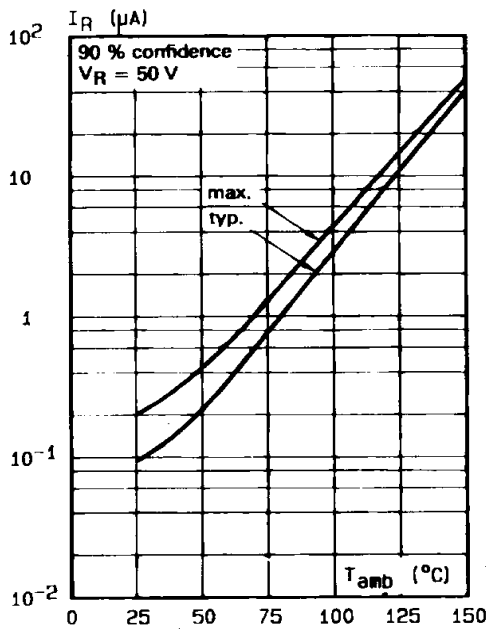
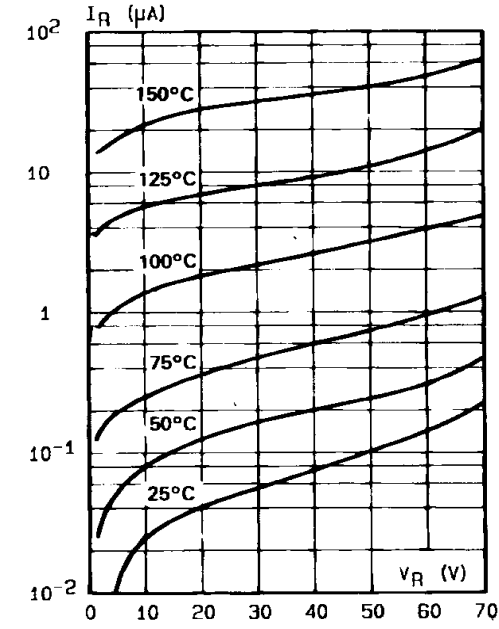
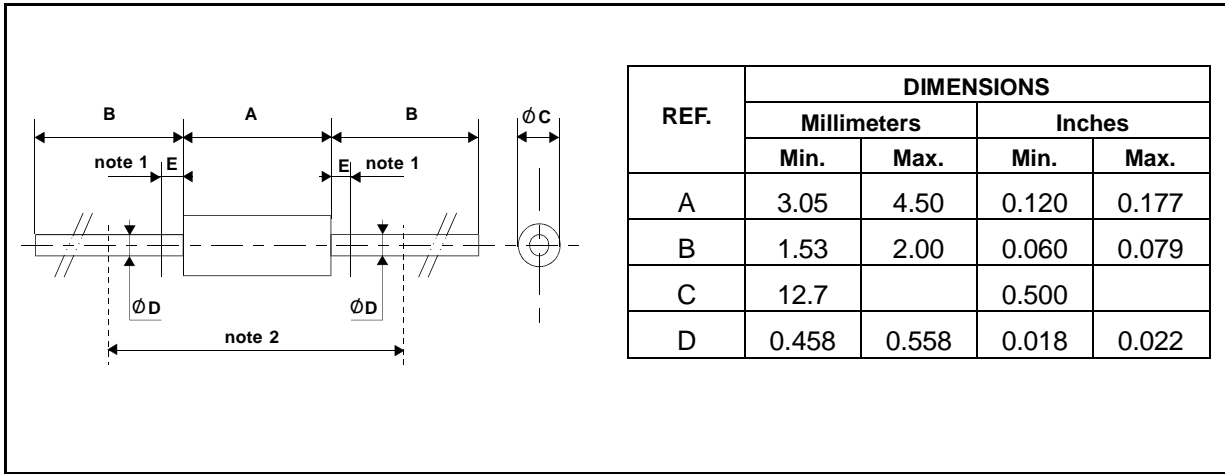


Figure 4. Reverse current versus continuous reverse voltage (typical values).



PACKAGE MECHANICAL DATA

DO 35 Glass



Cooling method : by convection and conduction
 Marking: clear, ring at cathode end.
 Weight: 0.15g

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